

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









## **Thin-film Diplexer**

For W-LAN

**TFSD Series** 

Type: TFSD10055950-5001C1

Issue date: June 2017



The products in this catalog will be or have been stopped production

<sup>•</sup> All specifications are subject to change without notice.

<sup>•</sup> Conformity to RoHS Directive: This means that, in conformity with EU Directive 2002/95/EC, lead, cadmium, mercury, hexavalent chromium, and specific bromine-based flame retardants, PBB and PBDE, have not been used, except for exempted applications.

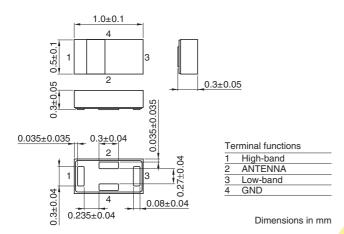
### **公TDK**

### **Thin-film Diplexer** For W-LAN

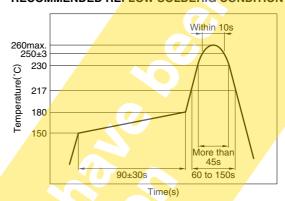
**Conformity to RoHS Directive** 

### TFSD Series TFSD10055950-5001C1

### **SHAPES AND DIMENSIONS**



### RECOMMENDED REFLOW SOLDERIG CONDITION



\* In this product, the recommended soldering condition is 'reflow'. Reflow Soldering: Maximum 2 times

### **RECOMMENDED PC BOARD PATTERNS**



Dimensions in mm

The recommended distance to the PCB ground plane is 0.2mm Line width be designed to mach 50Ω characteristic impedance depending on PCB Material and thickness.

### **ELECTRICAL CHARACTERISTICS**

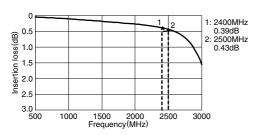
tem	Port	Frequency range		Minimum value	Typical value	Maximum value
Insertion loss	Low-band	2400 to 2500MHz	(dB)	_	0.43	0.5
	Hig <mark>h-band</mark>	4900 to 5950MHz	(dB)	_	0.49	0.65
Return loss	ANT	2400 to 2500MHz	(dB)	10	19.5	_
	ANT	4900 to 5950MHz	(dB)	10	20.4	_
	Low-band	2400 to 2500MHz	(dB)	10	21.4	_
	High-band	4900 to 5950MHz	(dB)	10	22.5	_
Attenuation	Low-band	4800 to 5000MHz	(dB)	20	23.1	_
	Low-band	7200 to 7500MHz	(dB)	20	29.2	_
	High-band	824 to 915MHz	(dB)	20	25.6	_
	High-band	1800 to 2500MHz	(dB)	20	24.1	_
	High-band	9800 to 11900MHz	(dB)	18	21.0	_
Isolation	High-band	DC to 2500MHz	(dB)	20	23.4	_
	High-band	4900 to 5950MHz	(dB)	20	23.9	_
Temperature range		Operating	(°C)	-40	_	+85
		Storage	(°C)	-40	_	+85

• Ta: +25°C

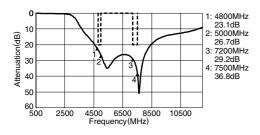
Conformity to RoHS Directive: This means that, in conformity with EU Directive 2002/95/EC, lead, cadmium, mercury, hexavalent chromium, and specific bromine-based flame retardants, PBB and PBDE, have not been used, except for exempted applications.

<sup>•</sup> All specifications are subject to change without notice.

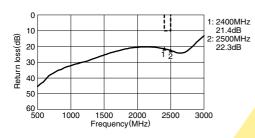
# FREQUENCY CHARACTERISTICS Low-BAND PORT INSERTION LOSS



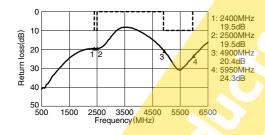
### **Low-BAND PORT ATTENUATION**



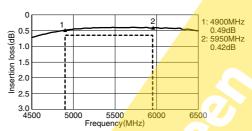
### **Low-BAND PORT RETURN LOSS**



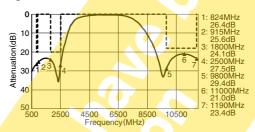
### **ANTENNA PORT RETURN LOSS**



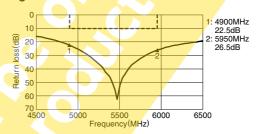
### **High-BAND PORT INSERTION LOSS**



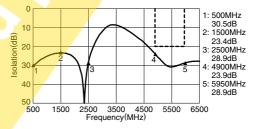
### **High-BAND PORT ATTENUATION**



### **High-BAND PORT RETURN LOSS**



### **ISOLATION (Low-High)**



<sup>•</sup> All specifications are subject to change without notice.